



Stock Symbol: 3167

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Ta Liang Technology Co., Ltd.

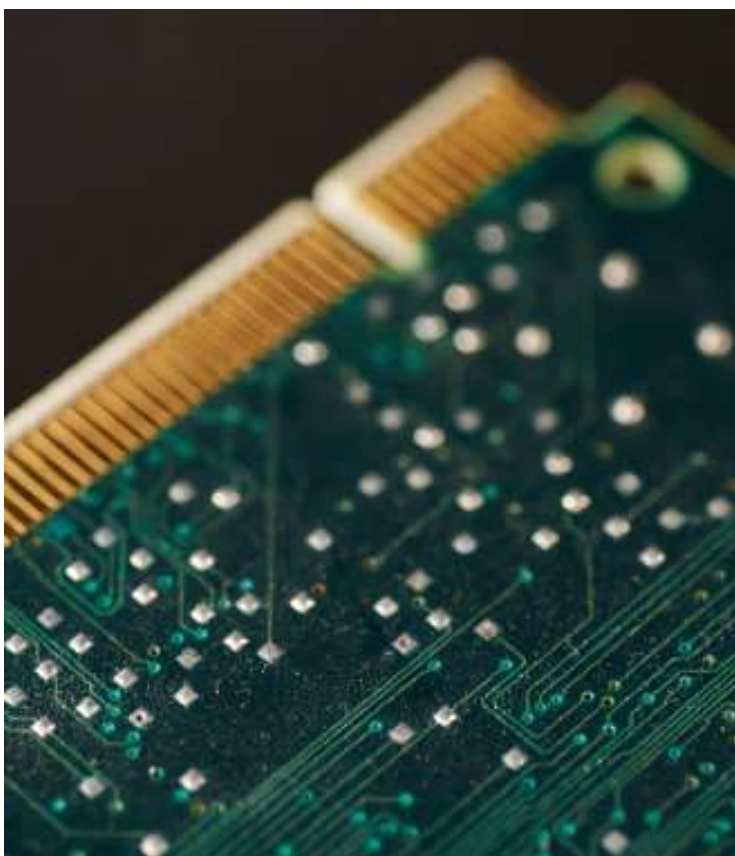


2026, Mar.

Disclaimer



- The predictive information mentioned in this presentation, including operational outlook, business situation, etc., is obtained by the Company through internal and external sources.
- The company's actual operational results that may occur in the future due to factors including but not limited to market competition and the conditions of international economy.
- The outlook for the future in this presentation is the Company's external views until now. For these views, if there are updates or adjustments in the future, the Company is not responsible for reminding or updating again at any time



Company Profile

Company Overview



Stock Symbol	3167
Capital	NTD 883,901,720
Chairman	Laurie Wang
General manager	Jackie Chien
Headquarter	No. 68, Fengtian Rd., Bade Dist. Taoyuan City, Taiwan (R.O.C.)
Factories	Bade 、Nanjing 、Lianshui





Business Scope

- Standard & High end PCB Drilling Machine
- Standard & High end PCB Routing Machine
- Automation
- Others

PCB BU



- Metrology Series
- AOI Series
- Automation Series

Semiconductor BU

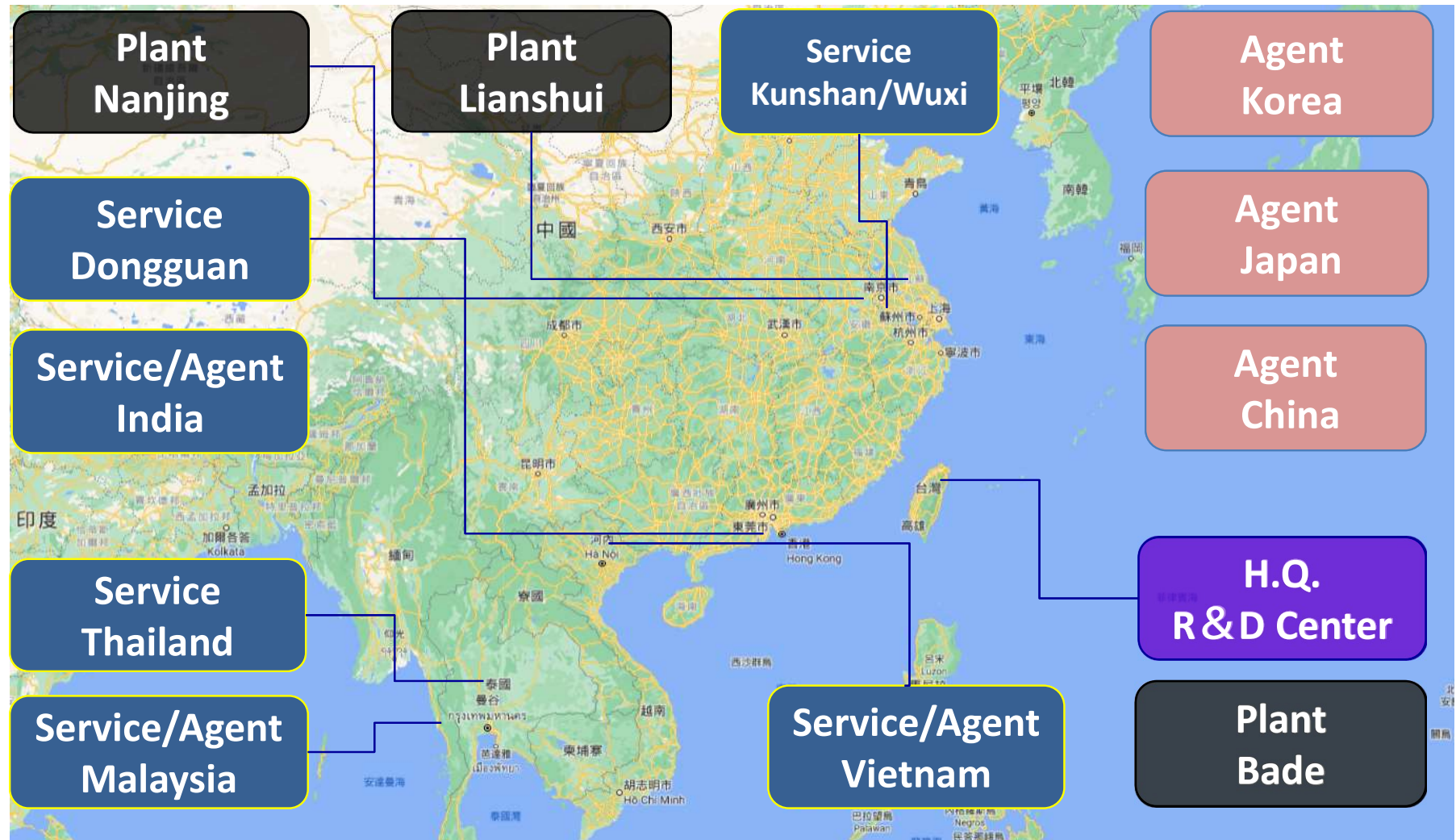


- R&D/purchasing/production/sales/service/management

TL Technology Team

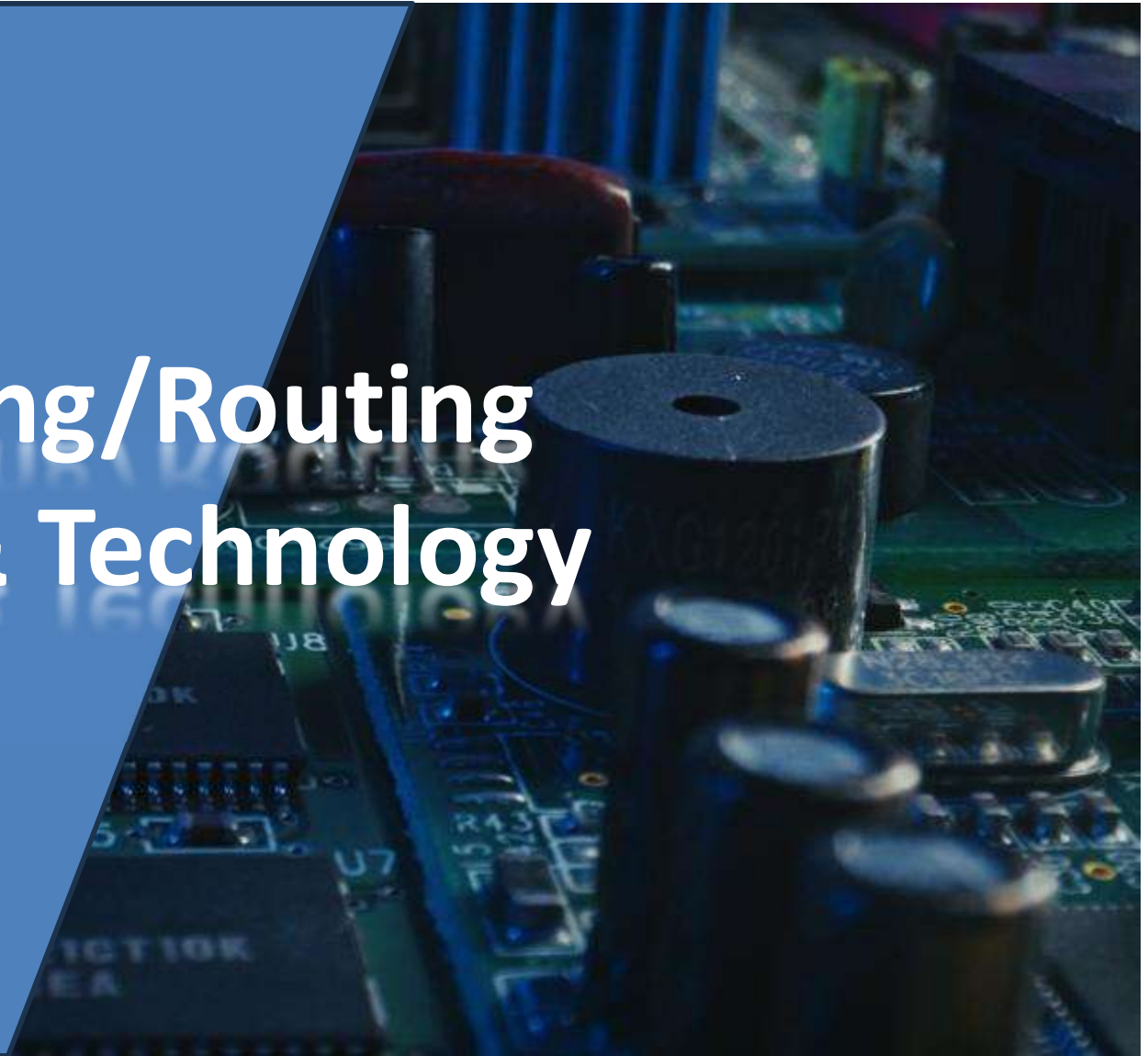


Production & Service Base





PCB Drilling/Routing Products & Technology



PCB BU main products



Drilling Machine



standard



CCD series



PCB Inner layer solution

PCB Router



standard



CCD series

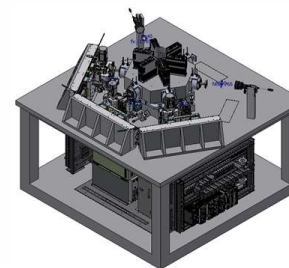


depth control

Edge Coater



1 station

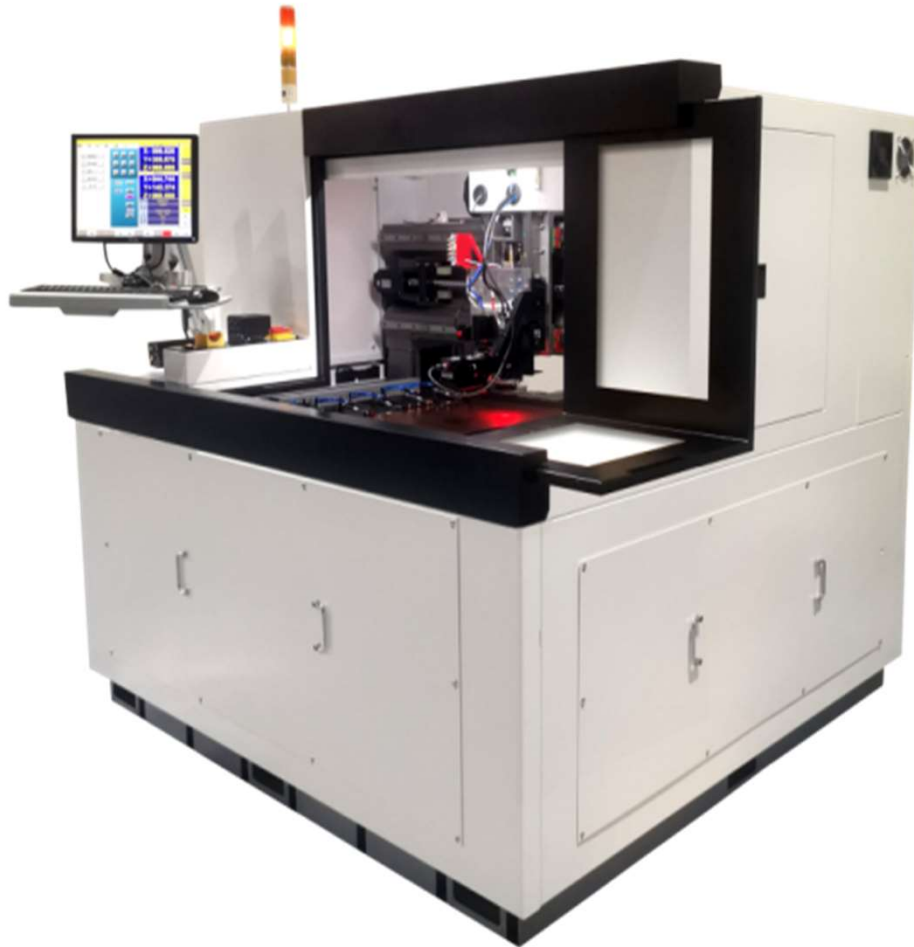


multi stations



PCB Inner layer Thickness Metrology -TM2

**Patent : (TW)I768701 / M627729 / I792823 / M622593
(CN) 6252475 / 16503982 / 16861153 / 9180563 / 15164943**



Features:

- TL developed controller
- PCB Thickness measurement module
- Inner layer depth measurement module
- For AI servo board, to solve the problem of unstable lamination, and excessive error between theoretical and actual value of target layer
- coordinate with CCD back drilling machine, to achieve high precise depth control capability



PCB Inner layer Thickness Metrology –TM3

**Patent : (TW)I768701 / M627729 / I792823 / M622593
(CN) 6252475 / 16503982 / 16861153 / 15164943**

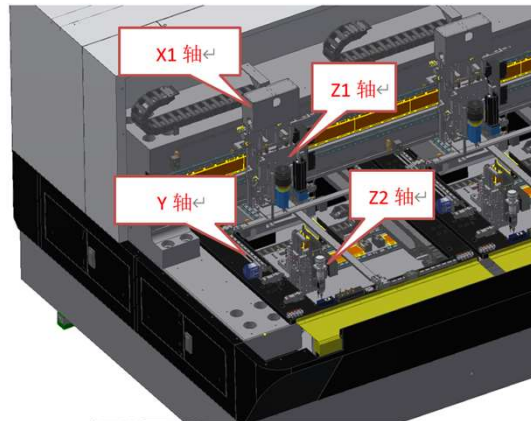


Features:

- TL developed Controller
- Board Thickness Measurement Module
- Inner Layer Trace Depth Module
- Overcomes excessive deviation between actual and theoretical non-break positions caused by unstable lamination quality in AI server boards.
- Integrates data with CCD backdrill machining to achieve highly precise alignment and depth-controlled drilling capability.

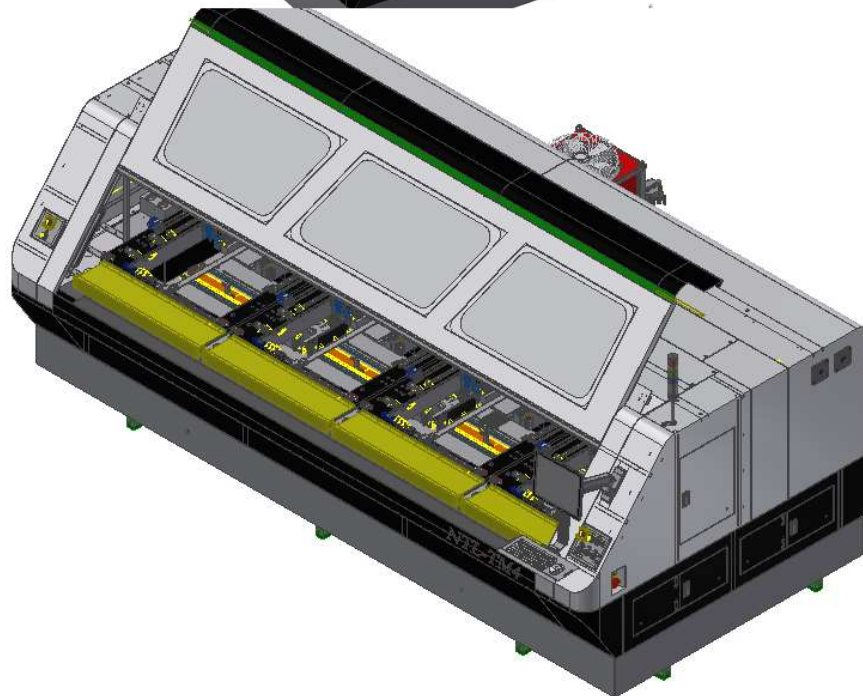


PCB Inner layer Thickness Metrology –TM4



Multiple Axis High-Efficiency Inner Layer Metrology

TM4 is a newly developed multiple-axis high-efficiency measurement machine designed for inner layer metrology. It delivers industrial-scale throughput with precision and speed optimized for mass production environments. TM4 combines advanced motion control and measurement technologies to achieve rapid, accurate copper feature analysis, significantly enhancing production efficiency and quality control.



PCB Inner layer Thickness Metrology

Patent Granted



Patent No.	Patent Title	Type	Filing Country
I768701	Optical System for Measuring Inner Layer Depth in PCBs	Invention	ROC
6252475	Optical System for Measuring Inner Layer Depth in PCBs	Invention	China
M627729 I792823	Optical Fiber System for Measuring Inner Layer Depth in PCBs	Invention	ROC
M622593	Periscope Optical System for Measuring Inner Layer Depth in PCBs	Utility Model	ROC
16503982	Periscope Optical Structure for Measuring Inner Layer Depth in PCBs	Utility Model	China
16861153	Optical Fiber System for Inner Layer Depth Measurement of Printed Circuit Boards	Utility Model	China
9180563	Machine for Inspecting Board Thickness and Copper Layer Depth (TM2)	Design Patent	China
15164943	PCB Inner Layer Depth Measurement Control Software V1.1.1	Software Copyright	China

PCB Inner layer Thickness Metrology



Pending Patent

Patent No.	Patent Title	Type	Filing Country
	Optical System for Measuring Inner Layer Depth in PCBs	Invention	China, Korea
	Optical System for Measuring Inner Layer Depth in PCBs	Invention	USA
	Module for Inner Layer Depth Measurement of PCB System and Operating Method for Inner Layer Depth Measuring of PCB Patent for TM2-Type Probe Rod for Measuring Holes	Invention	ROC
	System and Method for Measuring Inner Layer Depth in PCB Patent for TM2-Type Polishing Probe Rod for Hole Inspection	Invention	China
	Calibration System for Reflectance of Measured Objects	Utility Model	ROC, China
	Dual-Camera Module for PCB Inner Layer Depth Measurement (Tentative)	Utility Model	ROC, China
	Reflectance Calibration System for Measured Objects (Taiwan) Reflectance Calibration Device for Measured Objects (China)	Utility Model	China
	Optical Fiber System for Inner Layer Depth Measuring of PCB	Invention	China
	A Method for Copper Layer Inspection of PCB Boards	Invention	China
	Automated Inner Layer Circuit Inspection Machine	Invention	China
	Method for Inspecting Concentricity Between Through-Holes and Back-Drilled Holes in PCBs	Invention	China
	System and Method for Measuring Inner Layer Depth in PCB	Invention	China



TM Function introduction

Auto lighting sourcing change system

- Auto light source changing by controller to solve the board surface reflection issue

Tool cleaning

- Tool auto cleaning to reduce the measurement error by dust pollution issue on tool.

Sampling hole check

- For production efficiency, can set up hole check coverage and sampling rate

TL is the one and only in the industry capable of achieving
residual copper approaching 0 mil !



Required Precision

(1) PTH and Backdrill Hole Center Alignment Accuracy

D+10mil , D+8mil , D+6mil

(2) The residual copper length at the designated backdrill copper layer.

7±5 mil, 6±4mil, 6±3mil, 5+3(-2)mil

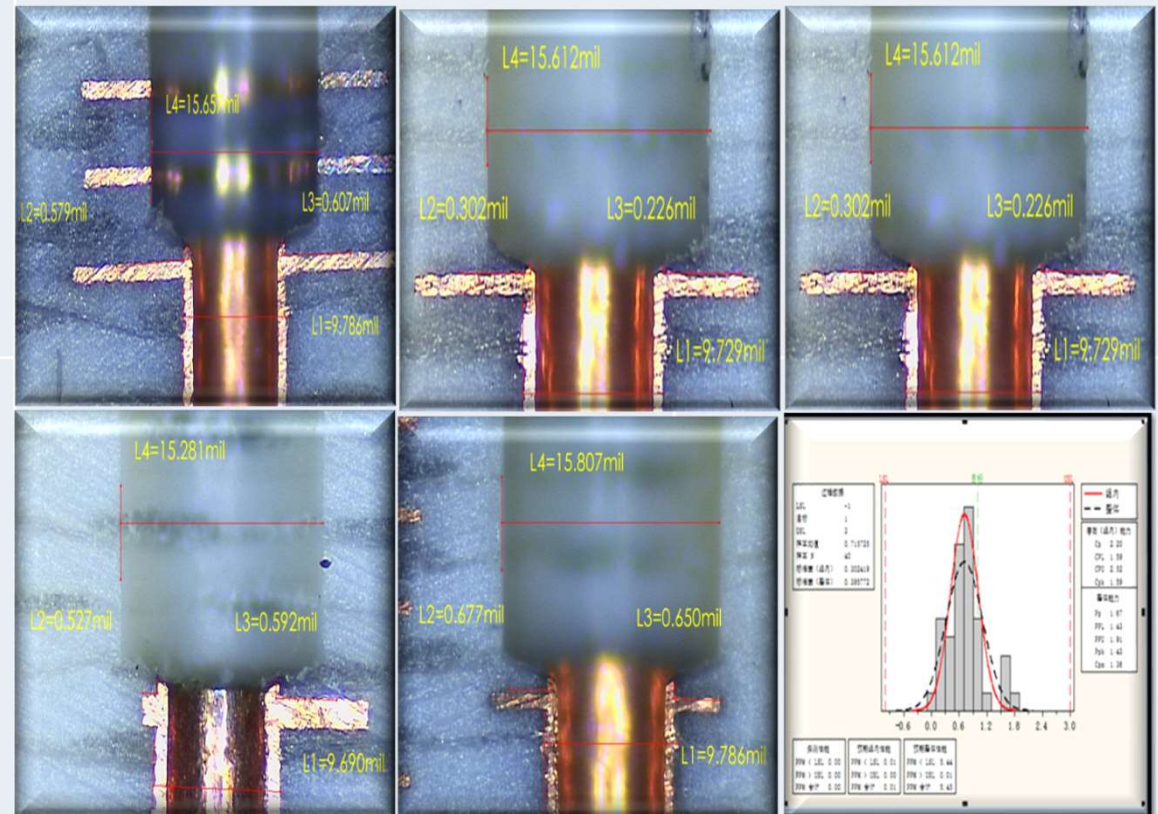
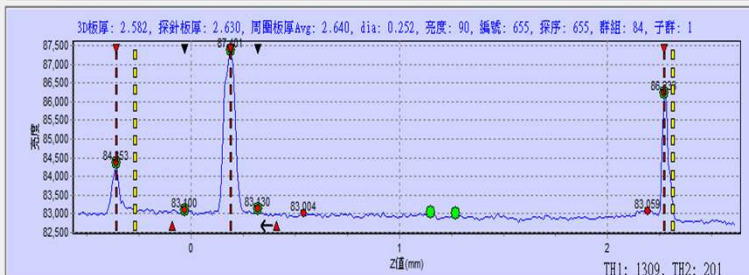
TL

D+4mil

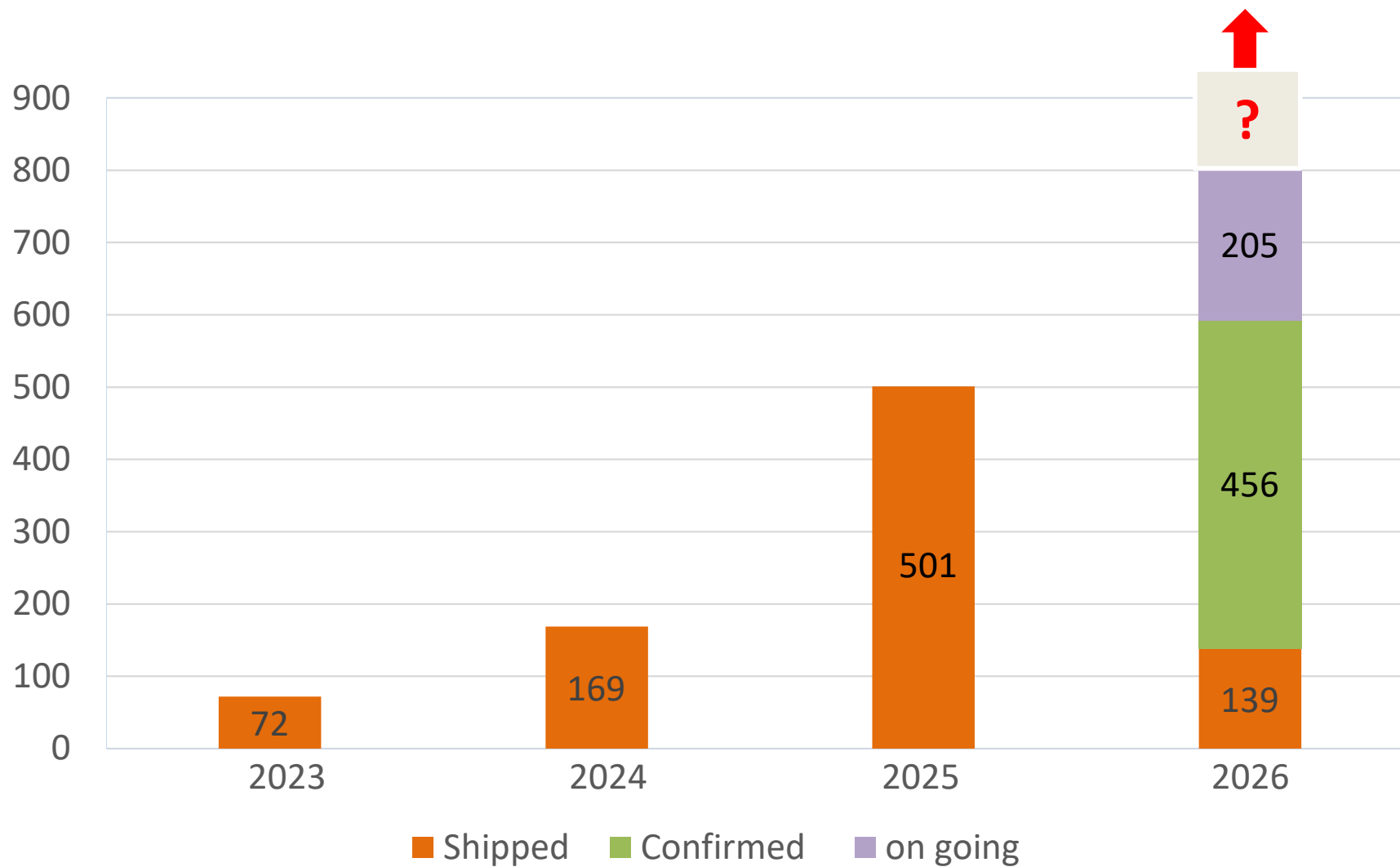
TL capability : 2 ± 2 mil , Cpk > 1.67

程式原點 | XY 偏移 | CCD 補償 | 板厚補償 | 3D XY 補償 | 3D 量測結果

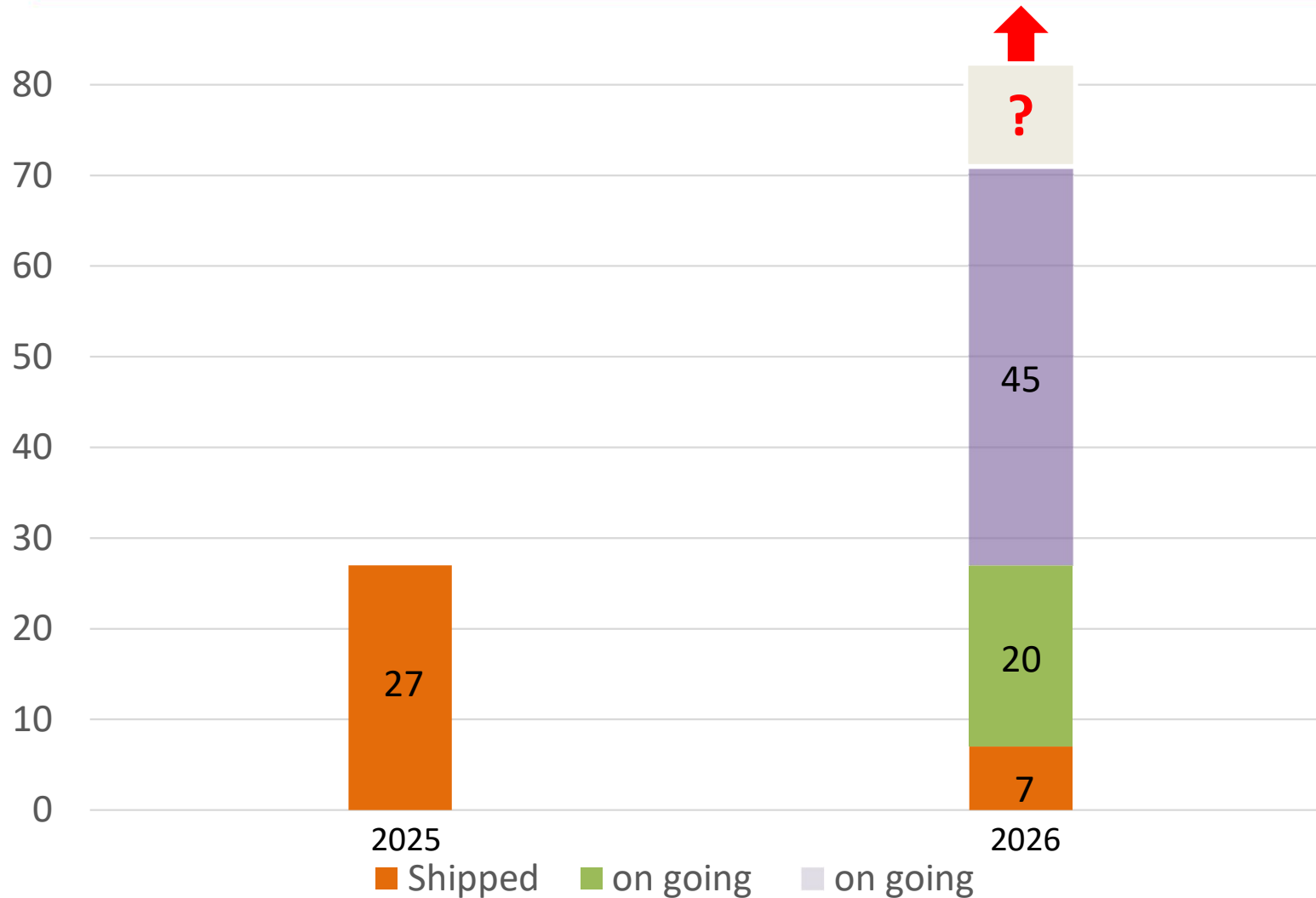
原始 車算	程式範圍		上下取最外層		順序探測		內層探尋距		抽探範圍		最小抽探數		首孔調		
	編號	X	Y	補償X	補償Y	3D上	3D下	探針上	探針下	內層1	內層2	內層3	程式X	指定內層	狀態
	651	-152.849	17.211	00.000	00.000	02.300	-0.262	02.280	-0.360	02.080	00.000	00.000	01.860	1	成功
	652	-152.849	17.922	00.000	00.000	02.479	-0.370	02.279	-0.361	02.080	00.000	00.000	01.860	1	成功
	653	-154.049	17.922	00.000	00.000	02.387	-0.399	02.287	-0.363	02.090	00.000	00.000	01.860	1	成功
	654	-154.049	17.211	00.000	00.000	02.315	-0.265	02.275	-0.365	02.090	00.000	00.000	01.860	1	成功
	655	-155.249	17.211	00.000	00.000	02.312	-0.270	02.272	-0.358	02.080	00.000	00.000	01.860	1	成功
	656	-155.249	17.922	00.000	00.000	02.382	-0.409	02.282	-0.358	02.100	00.000	00.000	01.860	1	成功
	657	-156.449	17.922	00.000	00.000	02.424	-0.300	02.274	-0.366	02.080	00.000	00.000	01.860	1	成功
	658	-156.449	17.211	00.000	00.000	02.345	-0.265	02.285	-0.365	02.100	00.000	00.000	01.860	1	成功
659	-157.650	17.211	00.000	00.000	02.299	-0.272	02.279	-0.361	02.080	00.000	00.000	01.860	1	成功	
660	-157.650	17.922	00.000	00.000	02.301	-0.324	02.281	-0.369	02.090	00.000	00.000	01.860	1	成功	



High-end Machine with CCD



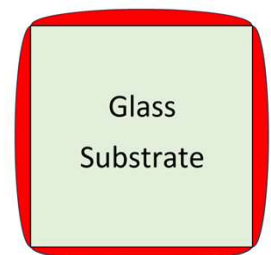
PCB Inner Layer Measurement Machine





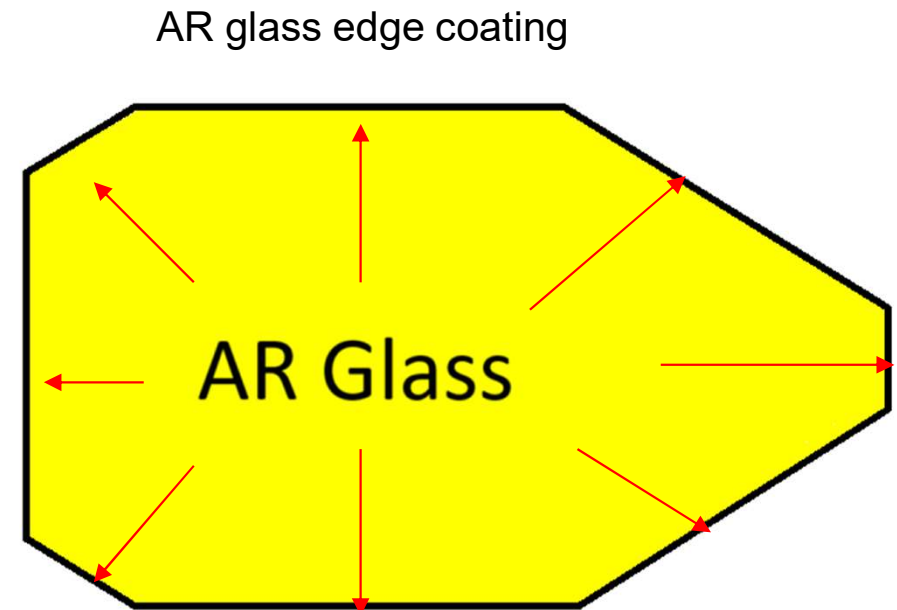
Edge Coater ensures precise and uniform application of protective layers on glass substrates, particularly at the edges where damage is most likely. It enhances mechanical strength, prevents chipping and moisture ingress, and maintains optical clarity.

Automated coating improves consistency, reduces waste, and boosts production efficiency, making it essential for high-quality glass substrate protection.



Light block out coatings on AR glass reduce glare and control ambient light, improving image clarity and contrast.

Precise application ensures a balance between transparency and light blocking for better visual experience.





Semiconductor Products & technology

Product Line-up



- CMP Pad Metrology
- Metrology Series

- Metrology Series
- AOI Series
- Automation Series



Product Line-up

Metrology Series

Wafer Trim-gap/Edge Profile
Metrology



AOI Series

Wafer Form AOI Machine



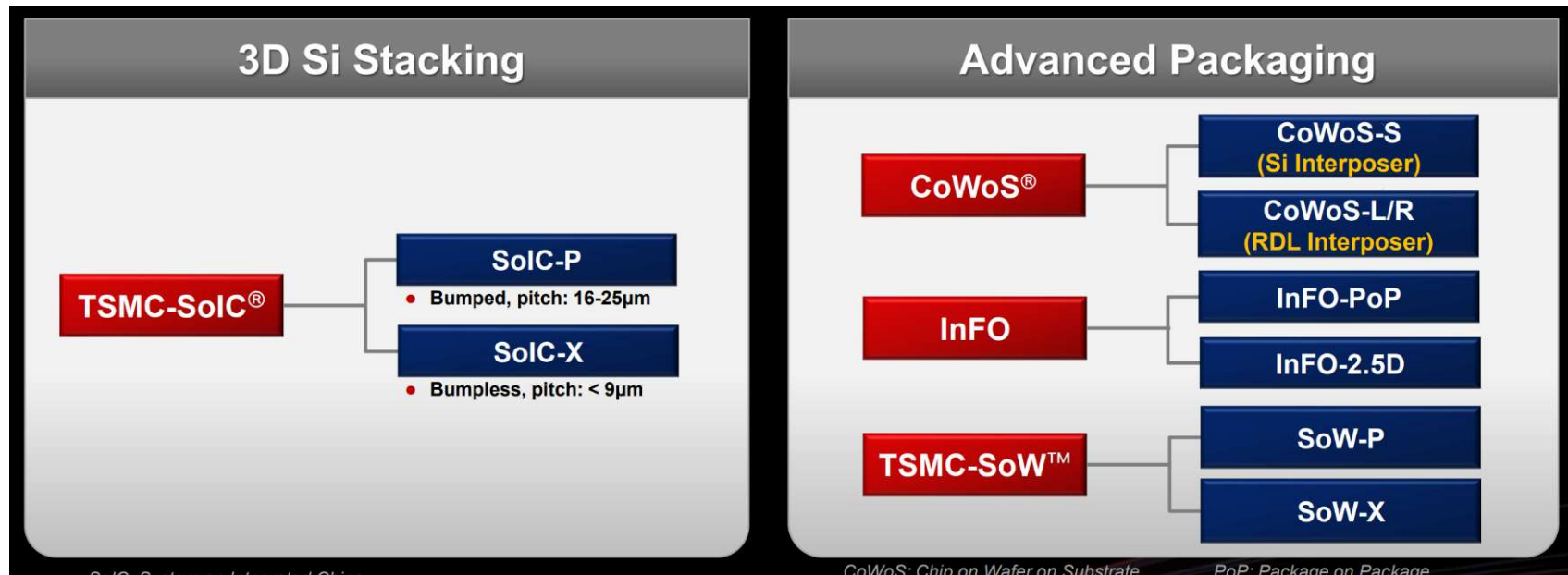
Product Line-up



Automation Series Carrier Transfer Machine

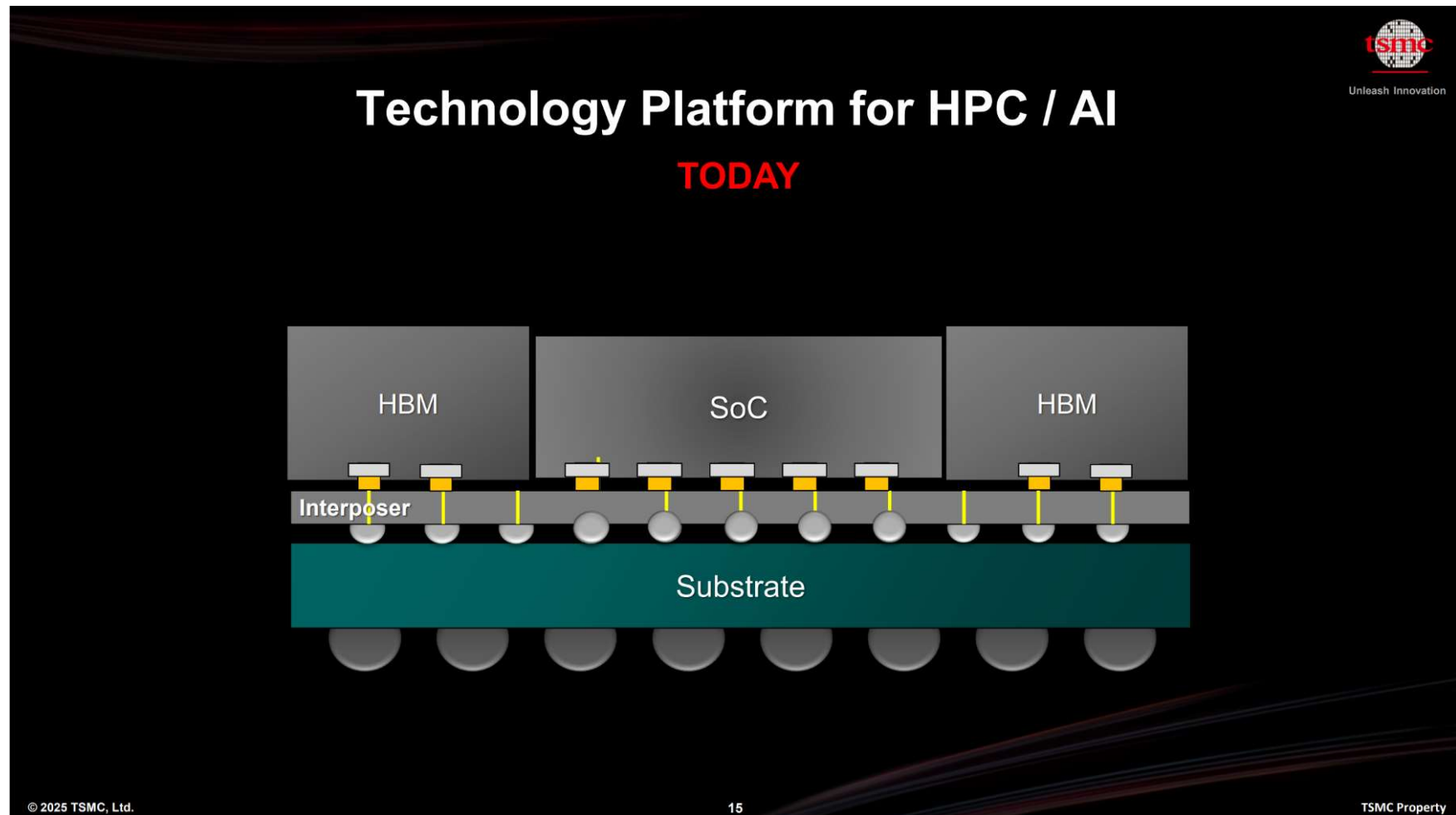


Advance Package-3D/2.5D Fabric





CoWoS(2.5D Fabric)-As is



3D IC Solution-CoW



HBM
Incoming AOI



Wafer Cosmetic AOI/
Warp Metrology



Wafer Flux Jetting AOI





3D IC Solution-CoW

Wafer Die Bond AOI



Wafer Underfill AOI
Fillet-height Metrology



Wafer Edge Die AOI



3D IC Solution-CoW



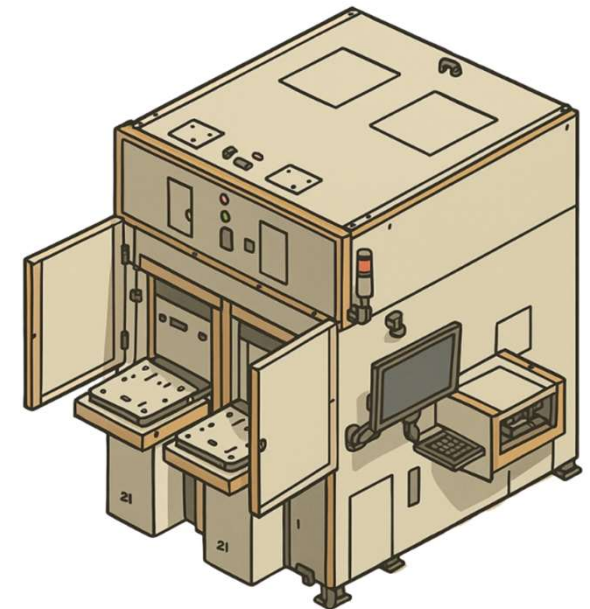
Wafer Molding AOI/
DUC/Thickness Metrology



Wafer IPD Die Bond AOI



EFEM+Buffer





3D IC Solution-(CoW)oS

Flux Jetting AOI



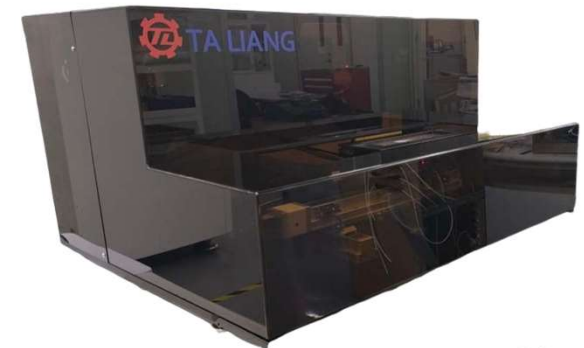
R2R AOI(FVI)



Die Bond AOI

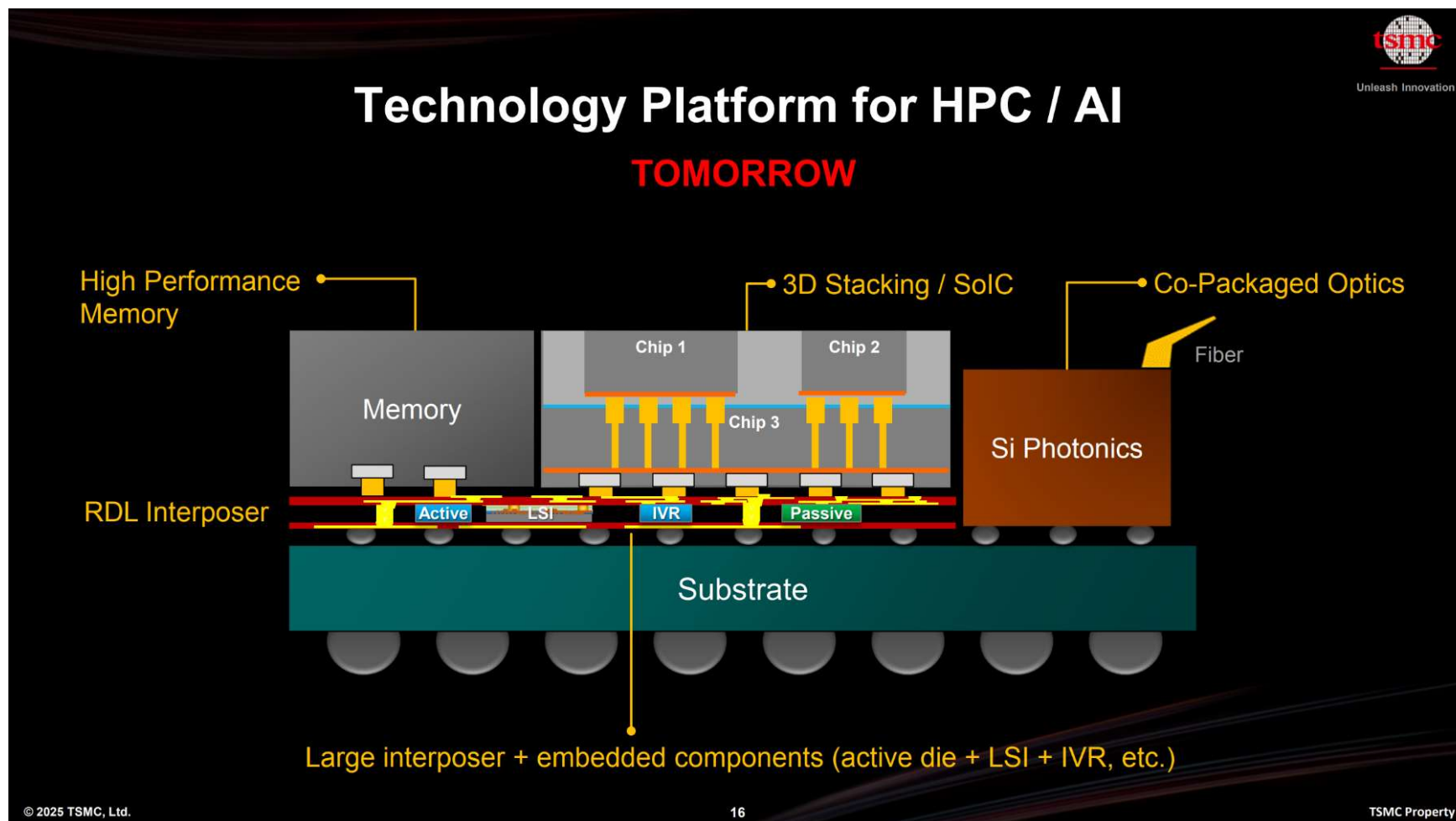


Bonding Tool
Metrology Platform





CoWoS(3D Fabric)-To be



3D IC Solution-SolC



CMP Pad Metrology



Step-height Metrology



Bonding Wafer
Edge Metrology



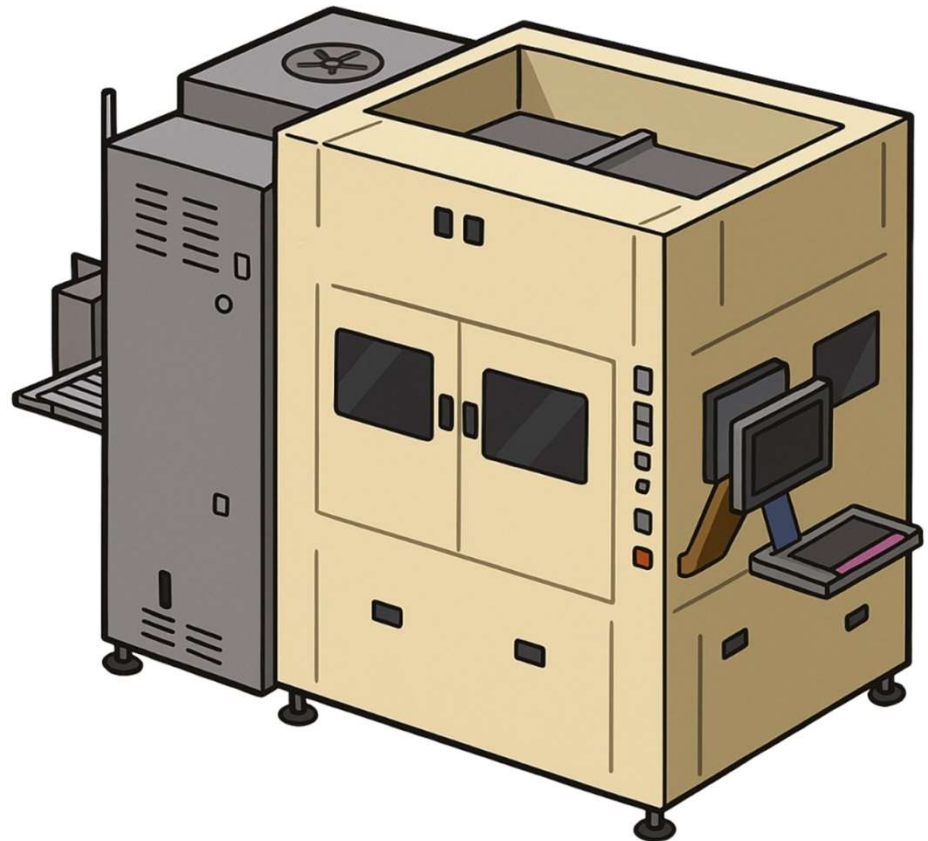


3D IC Solution-FOPLP(COP)

FOPLP Warpage Metrology



CoPoS Bond Shift_Edge Profile Metrology



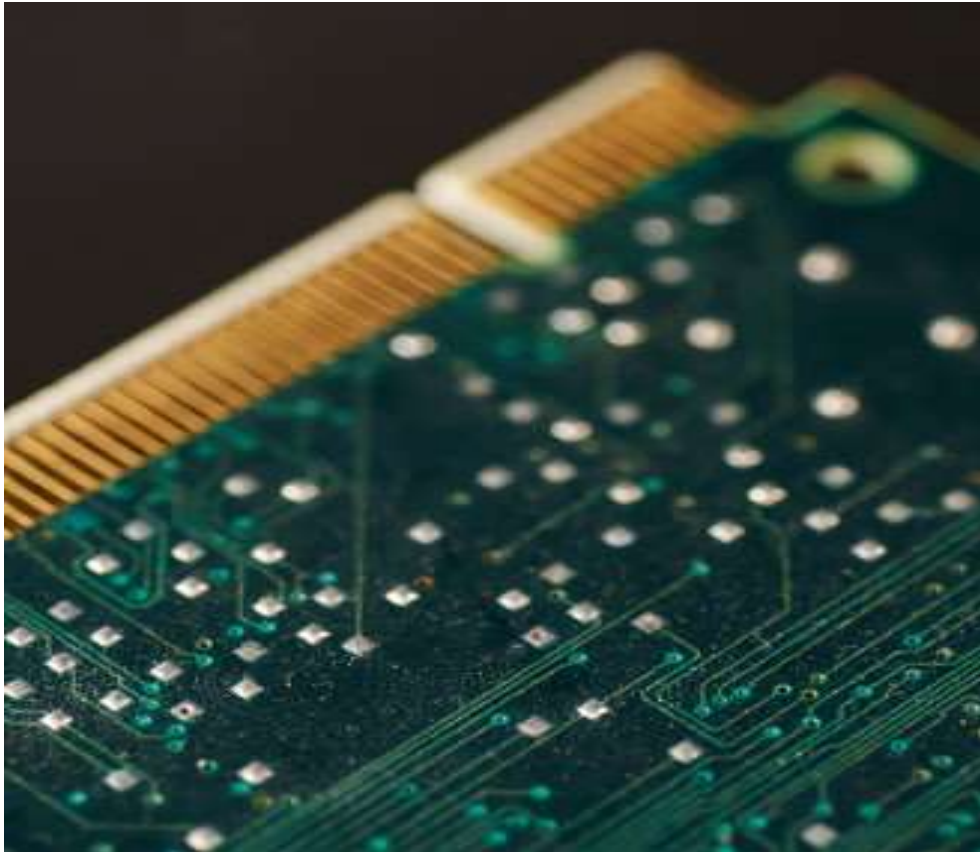


Customer List



台灣積體電路製造股份有限公司
Taiwan Semiconductor Manufacturing Company, Ltd.





Operational Performance

Income Statement



NTD Thousand	2025		2024	
	Amount	%	Amount	%
OPERATING REVENUE	5,077,937	100.00	2,599,385	100.00
OPERATING COSTS	3,088,936	60.83	1,848,519	71.11
GROSS PROFIT	1,989,001	39.17	750,866	28.89
OPERATING PROFIT (LOSSES)	916,429	18.05	72,079	2.77
PROFIT BEFORE INCOME TAX	970,735	19.12	148,610	5.72
NET PROFIT FOR THE PERIOD	716,187	14.10	124,395	4.79
BASIC EARNINGS PER SHARE(NTD)	8.13		1.48	

Thanks for your attention

